C7401

Conductor

Description

C7401 copper conductor is a practical alternative to precious metal materials in many applications. C7401 has been proven to resist ENIG plating solutions on alumina substrates. The advanced powder technology in C7401 results in improved fired film properties.

Key Features

- Exceptionally high conductivity Migration resistant ENIG plateable on alumina

This picture does not show the packaging of C7401 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Conductivity	≤ 4.0 milliohms/square at 15 um fired film thickness
Viscosity	120 – 180 Kcps, Brookfield HBTSC4 – 14 spindle and 6R cup at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Cu

Recommended Processing Guide	
Process Temperature (TDS)	Fire in Nitrogen with O2 between 2 – 10 ppm 900 °C peak Dwell time of 9 – 10 minutes Typical rise time of 20 – 23 minutes (measured from 100 °C entry point) Total cycle time of 50 – 65 minutes
Film Thickness	15 – 20 µm

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All changes are based on information displayed using the template data_sheet/HET/TFM/print_data_sheet.html.twig.
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